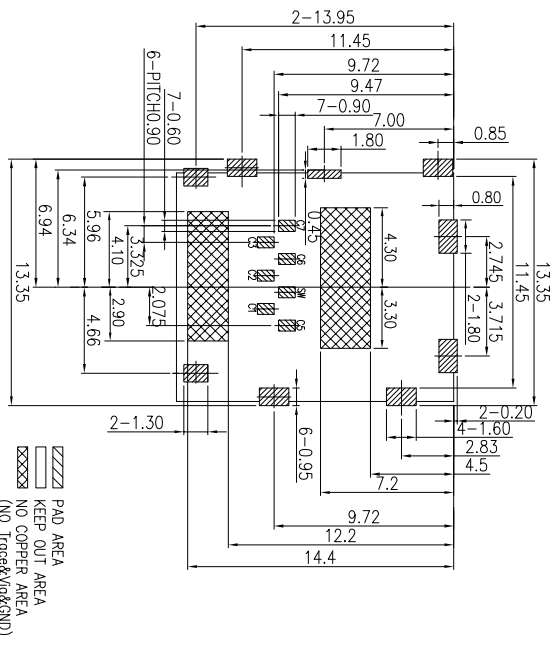
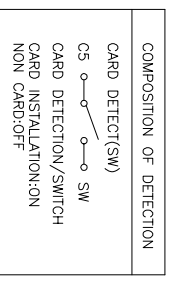


SIM Card Pin Assignments

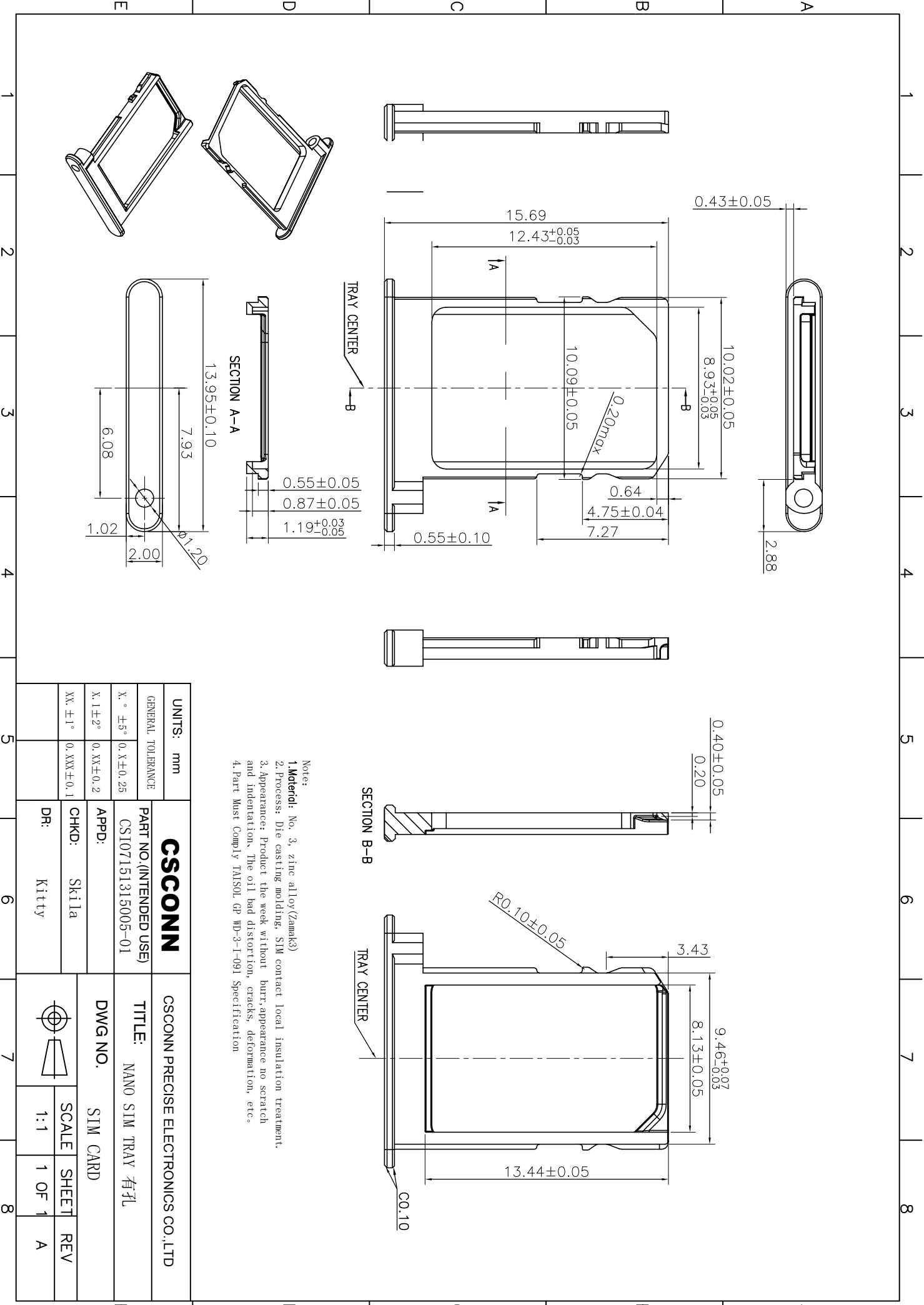
| NANO SIM CARD |       |
|---------------|-------|
| C1            | Vcc   |
| C2            | RST   |
| C3            | CLK   |
| C5            | GND   |
| SW            | CD/SW |
| C6            | Vpp   |
| C7            | DATA  |



- NOTE:
- Material:
    - 1-1 Housing: High Temperature Thermoplastic (LCP S475) Color Black UL 94V-0
    - 1-2 Contact: Phosphor Bronze (CS210R-HI=0.08±0.01mm)
    - 1-3 Cover: SUS301-HI T=0.15±0.03mm
  - Plating:
    - 2-1 Contact terminal: Gold 1μ Min.
    - 2-2 Contact area: Gold 0.8μ Min.
    - 2-3 Underplating: Ni overall 500μ Min.
  - Specification:
    - 3-1 Underplating: Ni overall 300μ Min.
    - 3-2 Solder area: Gold 0.8μ Min.
  - Current Rating: 0.5A max.
  - Resistance: 50 mΩ max
  - Insulation Resistance: 1000 MΩ min./500VDC
  - Dielectric Withstanding Voltage: 500 V AC/1minute
  - Operating Temperature: -25°C to +85°C
  - Mating Cycles: 5000 Insertions

- Product Compliant to Rohs Directive 2002/95/EC and ELV 2000/53/EC
- Part Must Comply Total HF WD-3-1-091 Specification.
- Recommending A Metal More Than 0.15mm Thick.
- Please Confirm Solderability, if Use A Metal Mask Less Than 0.15mm Thick.

| UNITS: mm         |           | <b>CSCONN</b>           |                                       | CSCONN PRECISE ELECTRONICS CO.,LTD |     |
|-------------------|-----------|-------------------------|---------------------------------------|------------------------------------|-----|
| GENERAL TOLERANCE |           | PART NO. (INTENDED USE) | TITLE: NANO SIM CARD PUSH 1.5H TYPE B |                                    |     |
| X ±.5°            | 0.XX±0.25 | CS107151315005          | DWG NO. SIM CARD                      |                                    |     |
| X 1±.2°           | 0.XX±0.2  | APPD:                   | SCALE                                 | SHEET                              | REV |
| XX ±1°            | 0.XX±0.1  | CHKD: Skilla            | 1:1                                   | 1 OF 1                             | A   |
|                   |           | DR: Kitty               |                                       |                                    |     |



- Note:
1. Material: No. 3, zinc alloy(Zamak3)
  2. Process: Die casting molding, SIM contact local insulation treatment.
  3. Appearance: Product the weak without burr, appearance no scratch and indentation, The oil bad distortion, cracks, deformation, etc.
  4. Part Must Comply TAIISOL (P WD-3-1-091) Specification

|                   |            |                        |  |                                    |  |        |  |
|-------------------|------------|------------------------|--|------------------------------------|--|--------|--|
| UNITS: mm         |            | <b>CSCONN</b>          |  | CSCONN PRECISE ELECTRONICS CO.,LTD |  |        |  |
| GENERAL TOLERANCE |            | PART NO.(INTENDED USE) |  | TITLE:                             |  |        |  |
| X. ° ±5°          | 0. X±0.25  | CS107151315005-01      |  | NANO SIM TRAY 有孔                   |  |        |  |
| X.1 ±2°           | 0. XX±0.2  | APPD:                  |  | DWG NO.                            |  |        |  |
| XX ±1°            | 0. XXX±0.1 | CHKD: Skila            |  | SIM CARD                           |  |        |  |
|                   |            | DR: Kitty              |  | SCALE                              |  | SHEET  |  |
|                   |            |                        |  | 1:1                                |  | 1 OF 1 |  |
|                   |            |                        |  |                                    |  | REV    |  |
|                   |            |                        |  |                                    |  | A      |  |